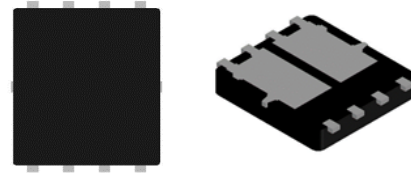


**FEATURES**

- Drain-Source Withstand Voltage: 40V
- Max.  $R_{DS(on)}$  : 8.9m $\Omega$  @  $V_{GS}=10V$   
13.5m $\Omega$  @  $V_{GS}=4.5V$
- Automotive applications
- AEC-Q101 Qualified
- Excellent ON resistance
- General footprint package PDFN5 $\times$ 6-8L
- 100% Rg and Avalanche tested
- MSL1

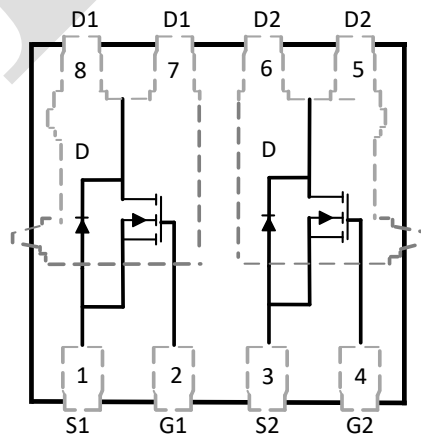
**PRODUCT APPEARANCE**

 PDFN5 $\times$ 6-8L

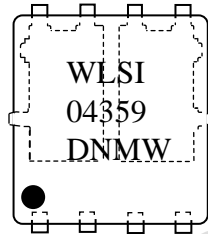
**DESCRIPTION**

The SND048R9DNAQ is N-Channel enhancement MOS Field Effect Transistor. Uses advanced trench technology and design to provide excellent  $R_{DS(ON)}$  with low gate charge. This device is suitable for use in high performance automotive DC-DC conversion, power switch and charging circuit. Standard Product SND048R9DNAQ is in compliance with RoHS.

**Applications:**

- Automotive systems
- DC/DC converters
- Power supply converters circuit
- Load/Power Switching for portable device

**PIN CONFIGURATION**


**MARKING**


WLSI = Company (Group) Code  
 04359 = Device Code  
 DN = Special Code  
 M = Month  
 W = Week

**LIMITING VALUES**

Parameter	Symbol	Condition	Value	Unit
Drain-Source Voltage	$V_{DS}$		40	V
Gate-Source Voltage	$V_{GS}$		$\pm 20$	V
Continuous Drain Current <sup>(4)</sup>	$I_D$	$T_C=25^\circ\text{C}$	48	A
		$T_C=100^\circ\text{C}$	34	A
Pulsed Drain Current <sup>(3)</sup>	$I_{DM}$		114	A
Continuous Drain Current	$I_D$	$T_A=25^\circ\text{C}$	12	A
		$T_A=100^\circ\text{C}$	9	A
Avalanche Energy $L=0.3\text{mH}$	$E_{AS}$		43.3	mJ
Power Dissipation <sup>(2)</sup>	$P_D$	$T_C=25^\circ\text{C}$	37	W
		$T_C=100^\circ\text{C}$	18	W
Power Dissipation <sup>(1)</sup>	$P_D$	$T_A=25^\circ\text{C}$	2.5	W
		$T_A=100^\circ\text{C}$	1.3	W
Operating Junction Temperature	$T_J$		-55 to 175	$^\circ\text{C}$
Storage Temperature Range	$T_{STG}$		-55 to 175	$^\circ\text{C}$

**THERMAL RESISTANCE RATINGS**

Single Operation					
Parameter		Symbol	Typical	Maximum	Unit
Junction-to-Ambient Thermal Resistance <sup>(1)</sup>	Steady State	$R_{\theta JA}$	49.8	59.8	°C/W
Junction-to-Case Thermal Resistance <sup>(2)</sup>	Steady State	$R_{\theta JC}$	2.9	4.1	

**ELECTRONICS CHARACTERISTICS**

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
<b>OFF CHARACTERISTICS</b>						
Drain-to-Source Breakdown Voltage	$BV_{DSS}$	$V_{GS}=0V$ , $I_D = 250\mu A$	40			V
Drain-to-Source Breakdown Voltage Temperature Coefficient	$BV_{DSS}/T_J$			18.2		mV/°C
Zero Gate Voltage Drain Current	$I_{DSS}$	$V_{DS}=40V$ , $V_{GS}=0V$ , $T_J=25^\circ C$			1	$\mu A$
		$V_{DS}=40V$ , $V_{GS}=0V$ , $T_J=125^\circ C$			100	$\mu A$
Gate-to-source Leakage Current	$I_{GSS}$	$V_{DS}=0V$ , $V_{GS}= \pm 20V$			$\pm 100$	nA
<b>ON CHARACTERISTICS</b>						
Gate Threshold Voltage	$V_{GS(TH)}$	$V_{GS}=V_{DS}$ , $I_D = 250\mu A$	1.3	1.7	2.1	V
Threshold Temperature Coefficient	$V_{GS(TH)}/T_J$			-4.7		mV/°C
Drain-to-source On-resistance <sup>(4)</sup>	$R_{DS(on)}$	$V_{GS} = 10V$ , $I_D = 10A$		7.4	8.9	m $\Omega$
		$V_{GS} = 4.5V$ , $I_D = 10A$		10.5	13.5	
<b>CHARGES, CAPACITANCES AND GATE RESISTANCE</b>						
Input Capacitance	$C_{ISS}$	$V_{GS} = 0V$ , $f = 1.0MHz$ , $V_{DS}=20V$		660		pF
Output Capacitance	$C_{OSS}$			197		
Reverse Transfer Capacitance	$C_{RSS}$			11.6		
Total Gate Charge <sup>(5)</sup>	$Q_{G(TOT)}$	$V_{GS}=10V$ , $V_{DS}=20V$ , $I_D = 10A$		9.5		nC
Gate-to-Source Charge <sup>(5)</sup>	$Q_{GS}$			1.8		
Gate-to-Drain Charge <sup>(5)</sup>	$Q_{GD}$			1.2		

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Gate Resistance	R <sub>g</sub>	f = 1MHz		2.6		Ω
<b>SWITCHING CHARACTERISTICS <sup>(5)</sup></b>						
Turn-On Delay Time	td(ON)	V <sub>GS</sub> =10V, V <sub>DS</sub> = 32V, I <sub>D</sub> =10A, R <sub>G</sub> =5Ω		3.0		ns
Rise Time	tr			24.0		
Turn-Off Delay Time	td(OFF)			11.4		
Fall Time	tf			16.2		
Body Diode Reverse Recovery Time	trr	I <sub>F</sub> =10A, dI/dt= 100A/μs		17.6		ns
Body Diode Reverse Recovery Charge	Q <sub>rr</sub>	I <sub>F</sub> =10A, dI/dt= 100A/μs		7.2		nC
<b>BODY DIODE CHARACTERISTICS</b>						
Forward Voltage <sup>(4)</sup>	V <sub>SD</sub>	V <sub>GS</sub> =0V, I <sub>S</sub> =10A	0.5	0.8	1.2	V

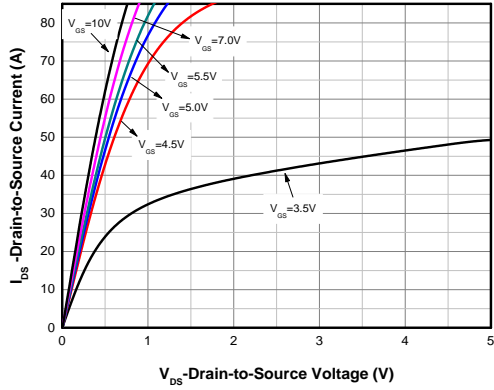
(T<sub>J</sub>=25°C, unless otherwise noted.)

**Note:**

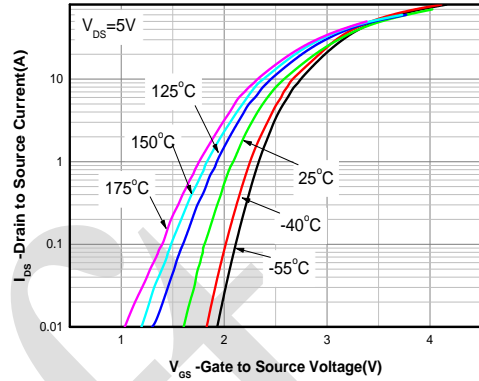
- (1) FR-4 board (38mm×38mm×t1.6mm, 70μm Copper) partially covered with copper (645mm<sup>2</sup> area). The power dissipation P<sub>DSM</sub> is based on Junction-to-Ambient thermal resistance value and the T<sub>J(MAX)</sub>=175°C. The value is only for reference, any application depends on the user's specific board design.
- (2) The power dissipation P<sub>D</sub> is based on T<sub>J(MAX)</sub>=175°C, using junction-to-case thermal resistance, and is more useful in setting the upper dissipation limit for cases where additional heat sinking is used.
- (3) Repetitive rating, pulsed, duty cycle ~1%, keep initial T<sub>J</sub>=25°C, the maximum allowed junction temperature of 175°C.
- (4) The static characteristics are obtained using ~380μs pulse, duty cycle ~1%.
- (5) The parameter is not subject to production test - verified by design / characterization.

**TYPICAL CHARACTERISTICS**

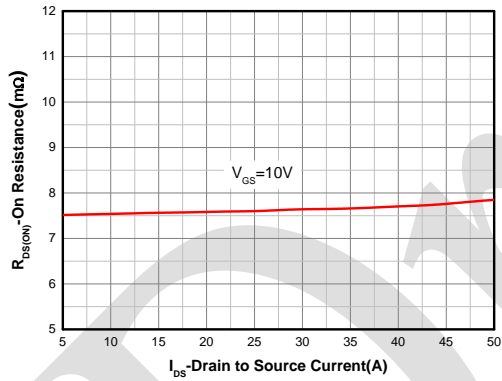
Ta=25°C, unless otherwise noted.



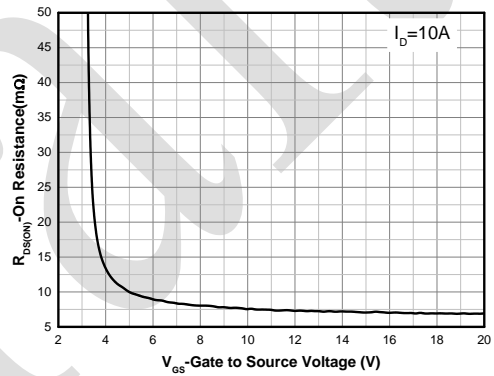
**Output Characteristics (4)**



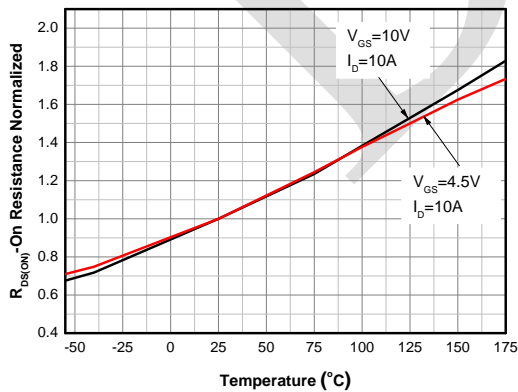
**Transfer Characteristics (4)**



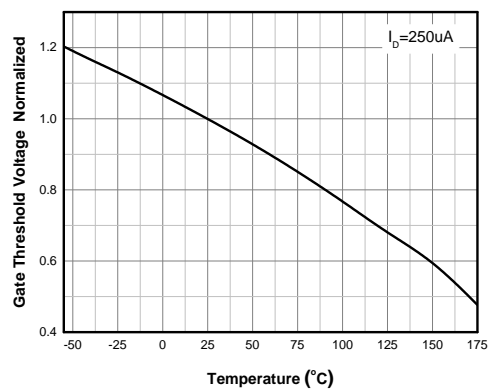
**On-Resistance vs. Drain Current (4)**



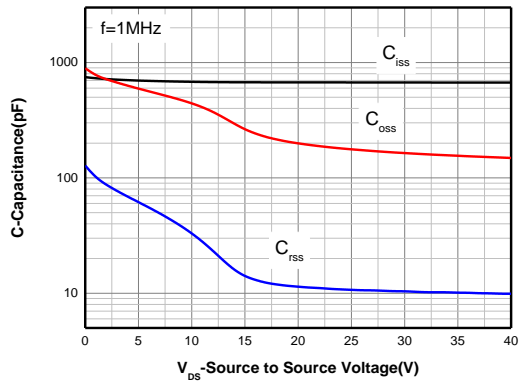
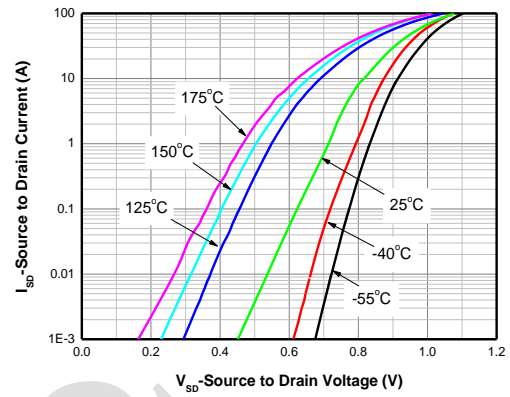
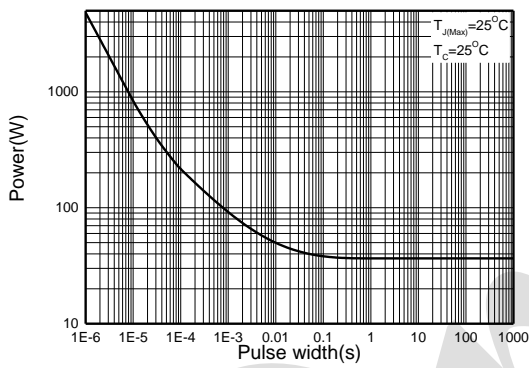
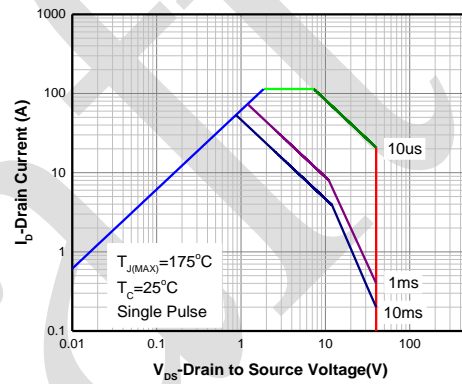
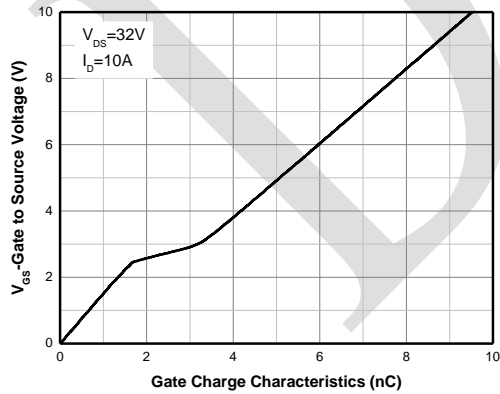
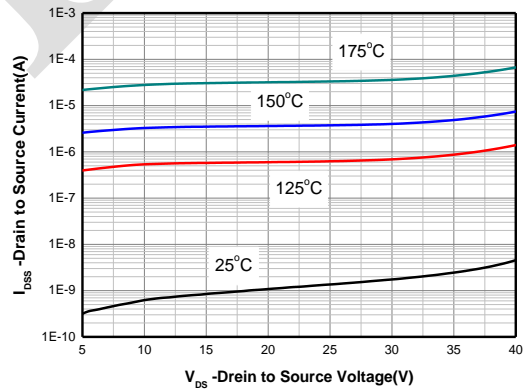
**On-Resistance vs. Gate-to-Source Voltage (4)**

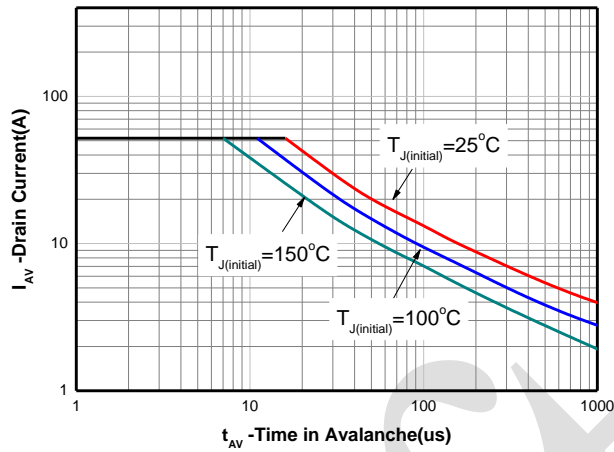
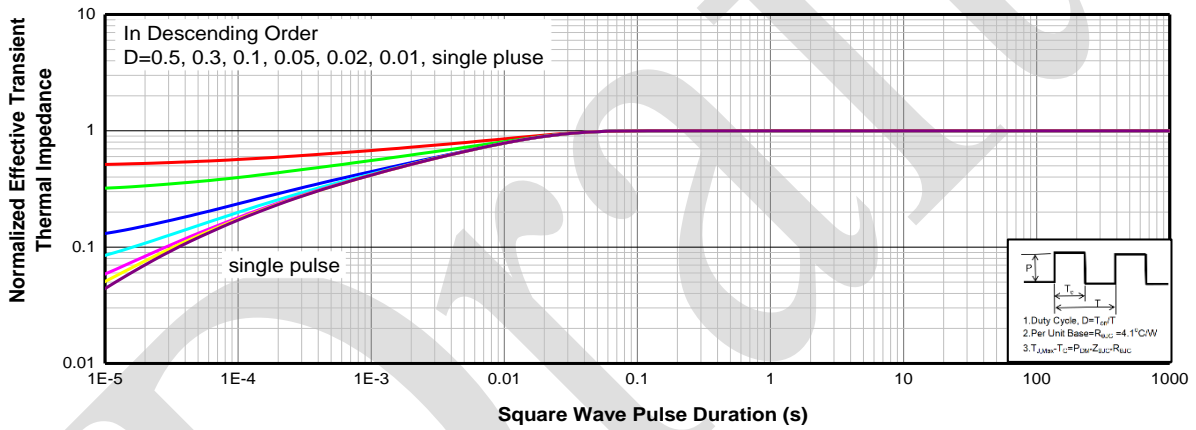
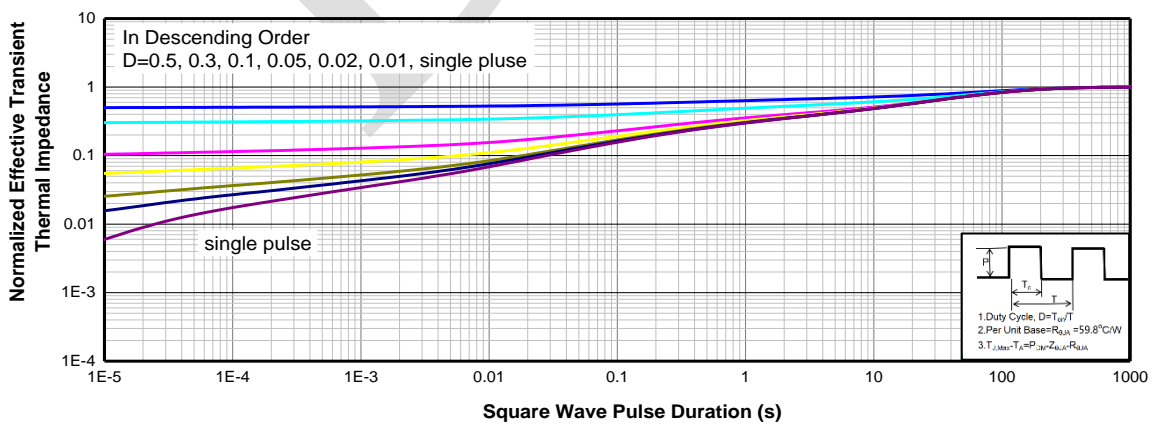


**On-Resistance vs. Junction Temperature (4)**



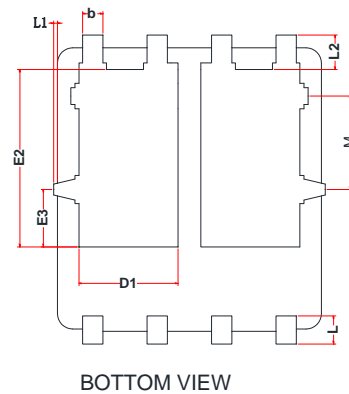
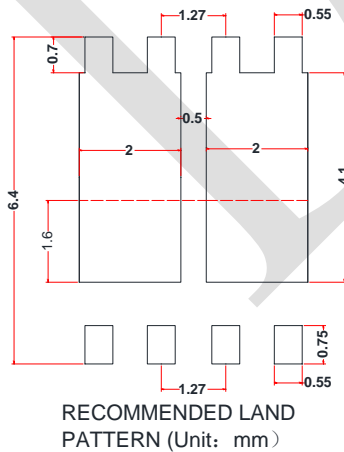
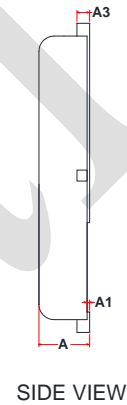
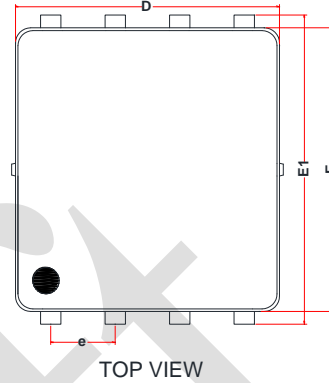
**Threshold Voltage vs. Temperature**


**Capacitance**

**Body Diode Forward Voltage <sup>(4)</sup>**

**Single Pulse power**

**Safe Operating Area**

**Gate Charge Characteristics**

**Drain Current vs. Drain Voltage**

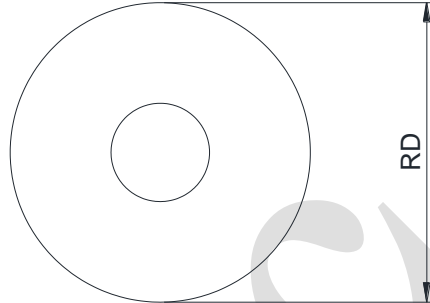
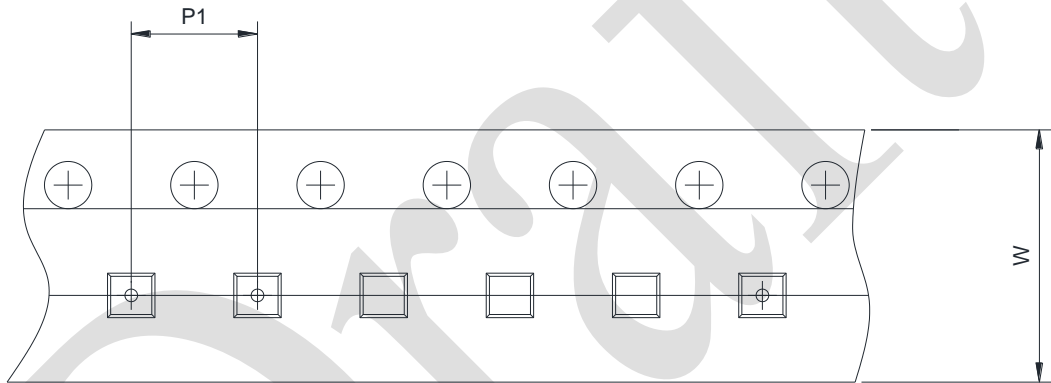
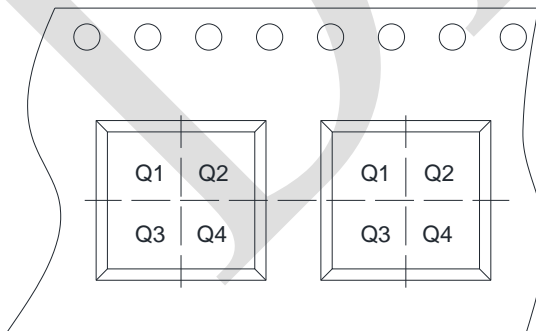

**Avalanche characteristics**

**Transient Thermal Response (Junction-to-Case)**

**Transient Thermal Response (Junction-to-Ambient)**

**PDFN5×6-8L DIMENSIONS**
**PACKAGE SIZE**

Symbol	Min.	Typ.	Max.
A	0.85	0.95	1.00
A1	0.00	---	0.05
A3	---	0.2 Ref	---
b	0.30	0.40	0.50
D	5.20 BSC		
E	5.55 BSC		
e	1.27 BSC		
D1	1.85	1.95	2.05
E1	5.95	6.05	6.15
E2	3.375	3.475	3.575
E3	1.025	1.125	1.225
L	0.45	0.55	0.65
L1	0	---	0.15
L2	0.675 Ref		
M	1.830Ref		





**TAPE AND REEL INFORMATION**
**Reel Dimensions**

**Tape Dimensions**

**Quadrant Assignments For PIN1 Orientation In Tape**


User Direction of Feed

RD	Reel Dimension	<input type="checkbox"/> 7inch	<input checked="" type="checkbox"/> 13inch
W	Overall width of the carrier tape	<input type="checkbox"/> 8mm	<input checked="" type="checkbox"/> 12mm <input type="checkbox"/> 16mm
P1	Pitch between successive cavity centers	<input type="checkbox"/> 2mm	<input type="checkbox"/> 4mm <input checked="" type="checkbox"/> 8mm
Pin1	Pin1 Quadrant	<input checked="" type="checkbox"/> Q1	<input type="checkbox"/> Q2 <input type="checkbox"/> Q3 <input type="checkbox"/> Q4

**ORDERING INFORMATION**

TYPE NUMBER	PACKAGE	PACKING
SND048R9DNAQ-8/TR	PDFN5×6-8L	Tape and reel

PDFN5×6-8L is packed with 5000 pieces/disc in braided packaging.

**Important statement**

SIT reserves the right to change the above-mentioned information without prior notice.

Draft

**REVISION HISTORY**

Version number	Datasheet status	Revision date
V0.2	Draft version.	May 2024

Draft